

TLP559(IGM)

- Transistor Inverters
- Air Conditioner Inverters
- Line Receivers
- Intelligent Power Modules (IPMs) Interfaces

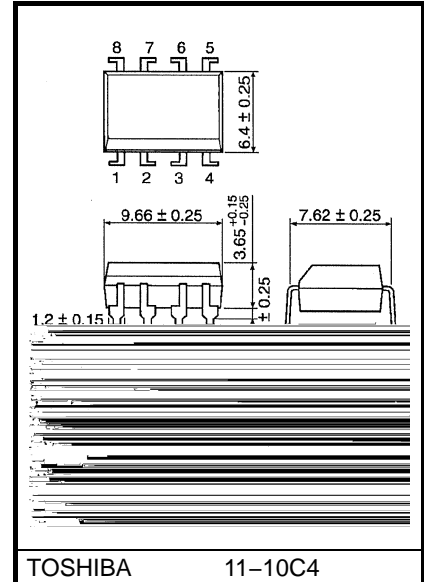
The TOSHIBA TLP559(IGM) consists of a high-output GaAIAs light emitting diode optically coupled to a high-speed photodiode with a transistor amplifier.

The TLP559(IGM) has no internal base connection. The Faraday shield in the photodetector chip provides an effective common-mode noise transient immunity.

The TLP559(IGM) guarantees minimum and maximum propagation delay times, a relative time difference between the rise and fall times, and common-mode transient immunity. Therefore, the TLP559(IGM) is suitable for an isolation interface between an Intelligent Power Module (IPM) and a control IC in motor control applications.

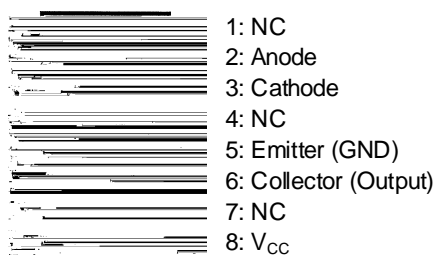
- Isolation Voltage: 2500 Vrms (min)
- Common-Mode Transient Immunity: ± 10 kV/ μ s (min) @ $V_{CM} = 1500$ V
- Switching Time: $t_{pHL}, t_{pLH} = 0.1 \mu$ s (min), $= 0.8 \mu$ s (max) @ $I_F = 10$ mA, $V_{CC} = 15$ V, $R_L = 20$ k Ω , $T_a = 25^\circ$ C
- Switching Time Dispersion: 0.7 μ s (max) ($t_{pLH} - t_{pHL}$)
- TTL Compatible
- UL Recognized: UL1577, File No. E67349

Unit: mm

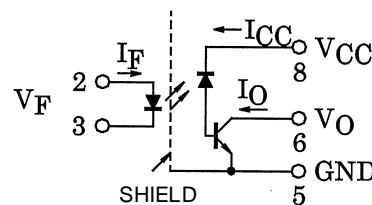


Weight: 0.54 g (typ.)

Pin Configuration (Top view)



Schematic



Absolute Maximum Ratings (Ta = 25°C)

| CHARACTERISTIC | | SYMBOL | RATING | UNIT |
|---|---|------------------|------------|------|
| LED | Forward Current (Note 1) | I _F | 25 | mA |
| | Pulse Forward Current (Note 2) | I _{FP} | 50 | mA |
| | Peak Transient Forward Current (Note 3) | I _{FPT} | 1 | A |
| | Reverse Voltage | V _R | 5 | V |
| | Diode Power Dissipation (Note 4) | P _D | 45 | mW |
| DETECTOR | Output Current | I _O | 8 | mA |
| | Peak Output Current | I _{OP} | 16 | mA |
| | Output Voltage | V _O | -0.5 to 20 | V |
| | Supply Voltage | V _{CC} | -0.5 to 30 | V |
| | Output Power Dissipation (Note 5) | P _O | 100 | mW |
| Operating Temperature Range | | T _{opr} | -55 to 100 | °C |
| Storage Temperature Range | | T _{stg} | -55 to 125 | °C |
| Lead Solder Temperature(10s) (Note 6) | | T _{sol} | 260 | °C |
| Isolation Voltage(AC,1min.,R.H. 60%,Ta=25°C) (Note 7) | | BV _S | 2500 | Vrms |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) Derate 0.8mA above 70°C.

(Note 2) 50% duty cycle, 1ms pulse width.
Derate 1.6mA/°C above 70°C.

(Note 3) Pulse width PW Ω ±1μs, 300pps.

(Note 4) Derate 0.9mW/°C above 70°C.

(Note 5) Derate 2mW/°C above 70°C.

(Note 6) Soldering portion of lead : up to 2mm from the body of the device.

(Note 7) Device considers a two-terminal device : pins1,2,3 and 4 shorted together and pins5,6,7 and 8 shorted together.

Electrical Characteristics (Ta = 25)

| CHARACTERISTIC | | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|----------------|---|-------------|---|------|------|------|---------|
| LED | Forward Voltage | V_F | $I_F = 16 \text{ mA}$ | | 1.65 | 1.85 | V |
| | Forward Voltage Temperature Coefficient | V_F / T_a | $I_F = 16 \text{ mA}$ | | -2 | | mV / °C |
| | Reverse Current | I_R | $V_R = 5 \text{ V}$ | | | 10 | μA |
| | Capacitance between Terminal | CT | $V = 0, f = 1 \text{ MHz}$ | | 45 | | pF |
| DETECTOR | High Level Output Current | $I_{OH(1)}$ | $I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$ | | 3 | 500 | nA |
| | | $I_{OH(2)}$ | $I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$ $V_O = 20 \text{ V}$ | | | 5 | μA |
| | | I_{OH} | $I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$ $V_O = 20 \text{ V}, T_a = 70^\circ\text{C}$ | | | 50 | |
| | High Level Supply Voltage | I_{CCH} | $I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$ | | 0.01 | 1 | μA |
| | Supply Voltage | V_{CC} | $I_{CC} = 0.01 \text{ mA}$ | 30 | | | V |
| | Output Voltage | V_O | $I_O = 0.5 \text{ mA}$ | 20 | | | V |

Coupled Electrical Characteristics (Ta = 25)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|--------------------------|-------------|---|------|------|------|------|
| Current Transfer Ratio | I_O / I_F | $I_F = 10 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $V_O = 0.4 \text{ V}$ | 25 | 35 | 75 | % |
| | | $I_F = 10 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $V_O = 0.4 \text{ V}, T_a = -25 \text{ to } 100^\circ\text{C}$ | 15 | | | |
| Low Level Output Voltage | V_{OL} | $I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $I_O = 2.4 \text{ mA}$ | | | 0.4 | V |

Isolation Characteristics (Ta = 25)

| CHARACTERISTIC | SYMBOL | TEST CONDITION | MIN. | TYP. | MAX. | UNIT |
|-----------------------------|--------|---|--------------------|-----------|------|------|
| Capacitance Input to Output | CS | $V = 0, f = 1 \text{ MHz}$ (Note 7) | | 0.8 | | pF |
| Isolation Resistance | R_S | R.H. $\Omega \pm 60\%$, $V_S = 500 \text{ V}$ (Note 7) | 5×10^{10} | 10^{14} | | T |
| Isolation Voltage | BV_S | AC, 1minute | 2500 | | | Vrms |
| | | AC, 1second, in oil | | 5000 | | |
| | | DC, 1minute, in oil | | 5000 | | Vdc |

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